



3D Packaging and Integration Global Technical Committee

Japan TC Chapter Meeting

Japan Standards Summer 2023 Meetings

Wednesday, June 21, 2023,

Web conference

To be conducted by Official Virtual TC Chapter Meeting

13:30-16:00 Japan Standard Time

AGENDA

1 Welcome / Call to Order

1.1 Introductions

1.2 Meeting Reminders (Membership Requirement, Antitrust and Intellectual Property Reminders, Effective Meeting Guidelines)

1.3 Agenda Review

2 Review of Previous Meeting of 3D Packaging & Integration Japan TC Chapter

3 Liaison Report

3.1 NA TC Chapter

3.2 Taiwan TC Chapter

4 Staff Report

5 Ballot Review

5.1 Cycle 2-2023 submitted by the Japan TC Chapter

5.1.1 6994 - Reapproval of SEMI G89-0211 (Reapproved 0318) Specification for Leadframe Strip Size

5.1.2 6995 -Reapproval of SEMI G71-0996 (Reapproved 0318) Specification for Barcode Marking of Intermediate Containers for Packaging Materials

5.1.3 6996 -Reapproval of SEMI G69-0996 (Reapproved 0318): Test Method for Measurement of Adhesive Strength Between Leadframes and Molding Compounds

5.1.4 6997 -Reapproval of SEMI G90-0811 (Reapproved 0318): Specification for 300 mm Wafer Coin-Stack Type Shipping Container Used for Test and Packaging Processes

5.1.5 6998 -Reapproval of SEMI G66-96 (Reapproved 0318):Test Method for the Measurement of Water Absorption Characteristics for Semiconductor Plastic

5.1.6 6999 -Reapproval of SEMI G23-0996 (Reapproved 0318): Test Method of Inductance for Internal Traces of Semiconductor Packages

6 Task Force & Study Group Reports

6.1 GCS



- 6.2 3D Packaging & Integration 5 Year Review Task Force
- 6.3 3DS IC Bonded Layer Inspection Metrology Task Force
- 6.4 Panel Level Packaging (PLP) Glass Carrier Task Force
- 6.5 3D Packaging & Integration Steering Group

7 Old Business

- 7.1 Project Period Review
- 7.2 5 Year Review Check

8 New Business

- 8.1 Proposal of New Activity

9 Action Item Review

- 9.1 Open Action Items
- 9.2 New Action Items

10 Next Meeting and Adjournment